Release Notes

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IEC60730B Safety Example

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by: NXP Semiconductors

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1 Introduction

These release notes describe important release information for the IEC60730B safety example application released together with the SDK v2.8.0.

All information about IEC60730B are at www.nxp.com/iec60730.

2 What is new

In the SDK v2.8.0 release, only certified library are available and they are listed in the following table:

Table 1. Device with available examples

Development board	Version of library
lpcxpresso845max	4.0
lpcxpresso824	4.0
lpcxpresso804	4.0
frdmkv11z	4.0
lpcxpresso55s69	4.0
evkmimxrt1020	3.0
evkmimxrt1060	3.0
evkbimxrt1050	3.0

3 Development tools

The safety IEC60730B example application was compiled and tested with the following development tools:

- IAR Embedded Workbench IDE version 8.50.1
- Arm[®]-MDK Keil[®] μVision[®] version 5.30
- MCUxpresso IDE version 11.2.0

FreeMASTER tool version 3.0 was used for application monitoring.

3.1 Debuggers

All projects (IAR, Keil, MCUxpresso) have the following debuggers set in the default configurations:



2

Table 2. Default board settings

Development board	Default debbuger	FreeMASTER communication chanell via	Serial communication speed
lpcxpresso845max	CMSIS-DAP	external debugger	-
lpcxpresso824max	CMSIS-DAP	external debugger	-
lpcxpresso804	CMSIS-DAP	external debugger	-
frdmkv11	PE micro	on-board debbuger	19200
lpcxpresso55s69	CMSIS-DAP	on-board debbuger	115200
evkmimxrt1020	CMSIS-DAP	on-board debbuger	19200
evkmimxrt1060	CMSIS-DAP	on-board debbuger	19200
evkbimxrt1050	CMSIS-DAP	on-board debbuger	19200

4 Known issues

This chapter contains the description of known issues or non-stantdard behavior of the released example.

FreeMASTER over externall J-link debugger on LPC8xx

In the safety examples, the LPC8xx device does not use FreeMASTER monitoring over an on-board debugger (via serial line), but it is set to use an external debbuger to connect to FreeMASTER.

To use an external Segger J-link, follow these steps:

- · Connect the SWD cable to the corresponding connector (connect it to the target MCU and not to the on-board debugger).
- Set the J-link debugger in the project file.
- · Donwload the application example onto the board.
- Open the FreeMASTER *.pmp file and set the correct conection in "Project-> Options ->Comm":

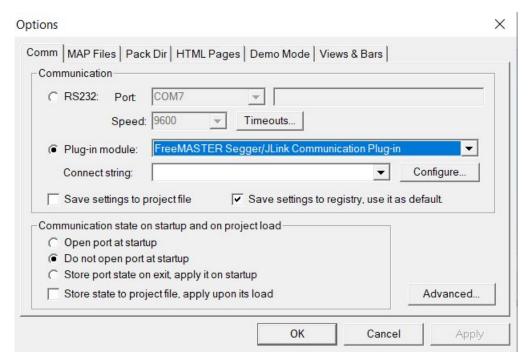


Figure 1. Setting J-link communication in FreeMASTER

Click "OK" and continue with a serial conection as usual.

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